



(1,00 mm) .0394"

MLE-150-01-G-DV

MLE-120-01-G-DV

CLM-111-02-L-D

CLM-126-02-F-D

CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn over 50µ" (1,27 µm) Ni
MLE: Au over 10µ" (0,25 µm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(1 pin powered per row)

Current Rating (MLE/FTM):

2.9 A per pin

(1 pin powered per row)

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

CLM: 15 mΩ

Max Cycles:

CLM: 100 with 10µ" (0,25 µm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1,40 mm)

.055" min., Bottom Entry =

(2,41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1,63 mm) .064" to

(3,18 mm) .125" with

(0,38 mm) .015" wiper,

pass-through, or

(2,44 mm) .096" minimum

for bottom entry

Insertion Force:

CLM: 1.5 oz (0,42 N) average

MLE: 2.70 oz (0,75 N) average

Normal Force:

CLM: 40 grams (0,39 N) average

Withdrawal Force:

CLM: .75 oz (0,21 N) average

MLE: 0.50 oz (0,14 N) average

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (02-25)

(0,15 mm) .006" max (26-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

CLM

Mates with:
FTM, FTMH, MW

1

NO. PINS PER ROW

02 thru 50

02

PLATING OPTION

-F
= Gold flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

D

OPTIONS

-BE
= Bottom Entry (Required for bottom entry)

-K
= (3,50 mm) .138" DIA Polyimide film Pick & Place Pad (7 positions minimum)

-P
= Pick & Place Pad (7 positions minimum)

-PA
= Pick & Place Pad with integral Alignment Pin

-TR
= Tape & Reel Packaging

APPLICATION

Pass-Thru

PIN/ROW	A
04-15	(3,56) .140
16-50	(7,11) .280

MLE

Mates with:
FTM, FTMH, MW

1

NO. PINS PER ROW

02 thru 50

01

PLATING OPTION

-G
= 10µ" (0,25 µm) Gold

DV

OPTIONS

-A
= Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion.

-K
= (4,00 mm) .1575" DIA Polyimide film Pick & Place Pad (5 positions minimum)

-P
= Metal Pick & Place Pad (5 positions minimum)

-TR
= Tape & Reel Packaging